

Part Number: XZBBR155W5MAV

0.65 x 0.35 x 0.2 mm SMD Chip LED Lamp

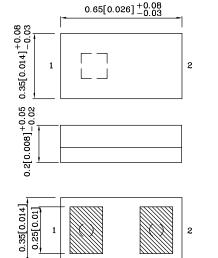
Features

- Ideal for indication light on hand held products
- Long life and robust package
- Standard Package: 4,000pcs/ Reel
- MSL (Moisture Sensitivity Level): 2
- Low current IF = 5mA operating
- RoHS compliant





Package Schematics



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<u>0.35[0.014]</u> 0.25[0.01] 1			2		
0.55[0.022]					

Notes:

1. All dimensions are in millimeters (inches).

- 2. Tolerance is $\pm 0.1(0.004")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)	Blue (InGaN)	Unit		
Reverse Voltage V _R		5	V	
Forward Current I		10	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	50	mA	
Power Dissipation		32	mW	
Electrostatic Discharge Threshold (HBM)		1000	V	
Operating Temperature	$T_{\rm A}$	$-40 \sim +85$	°C	
Storage Temperature	Tstg	-40 ~ +85	C	

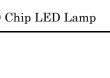
A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

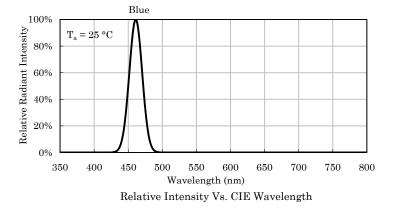
Operating Characteristics (T _A =25°C)	Blue (InGaN)	Unit	
Forward Voltage (Typ.) (I _F =5mA)	V_{F}	2.9	V
Forward Voltage (Max.) (I _F =5mA)	V_{F}	3.1	V
Reverse Current (Max.) (V _R =5V)	I_R	50	μΑ
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =5mA)	λP	461*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I _F =5mA)	λD	467*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =5mA)	$ riangle\lambda$	22	nm

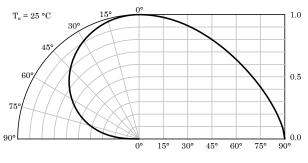
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity CIE127-2007* (I _F =5mA) mcd		Wavelength CIE127-2007* nm λΡ	Viewing Angle 20 1/2
				min.	typ.		
XZBBR155W5MAV	Blue	InGaN	Water Clear	15^{*}	24*	461*	140°

*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.



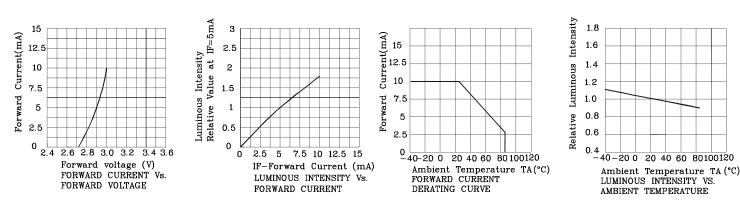


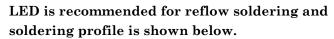


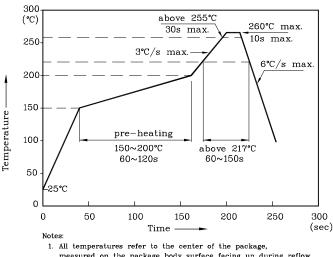


Spatial Distribution

Slue







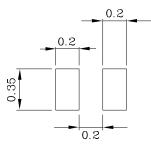
Reflow Soldering Profile for SMD Products (Pb-Free Components)

measured on the package body surface facing up during reflow. 2. Do not apply any stress to the LED during high temperature conditions. 3. Maximum number of soldering passes: 2



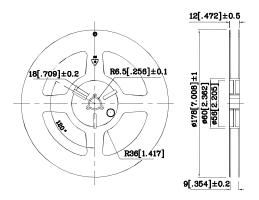
♦ The device has a single mounting surface. The device must be mounted according to the specifications.

Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)

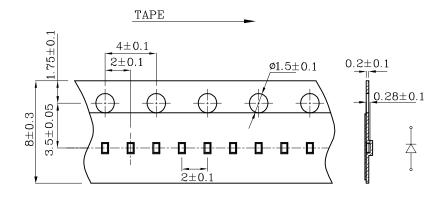


Mask open area ratio:80% Mask thickness:80~100um

Reel Dimension



Tape Specification (Units : mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm

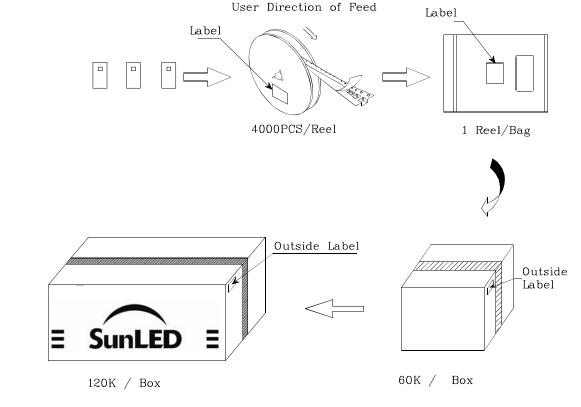
2. Luminous intensity / luminous flux: +/-15%

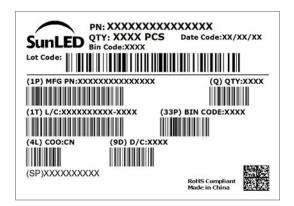
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.



PACKING & LABEL SPECIFICATIONS





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- 2. Contents within this document are subject to improvement and enhancement changes without notice.
- 3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet.
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- 6. Additional technical notes are available at https://www.SunLEDusa.com/TechnicalNotes.asp

Feb 28,2019

XDSB8231 V7-Z Layout: Maggie L.